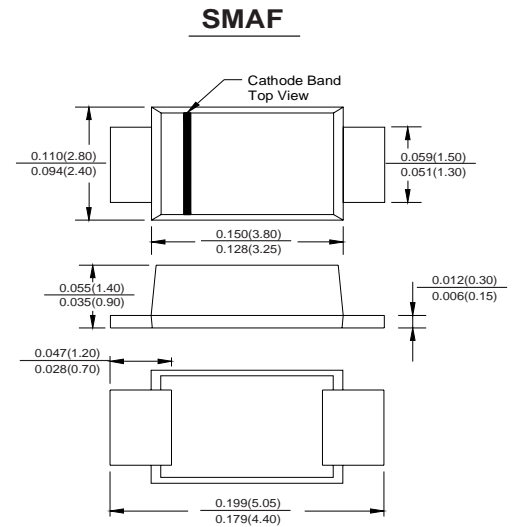


## FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

## MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg 0.00086oz



Dimensions in inches and (millimeters)

## Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

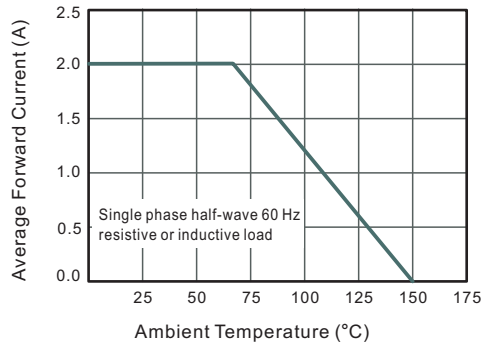
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a = 65\text{ }^{\circ}\text{C}$	$I_{F(AV)}$	2							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	60							A
Maximum Instantaneous Forward Voltage at 2 A	$V_F$	1.1							V
Maximum DC Reverse Current $T_a = 25\text{ }^{\circ}\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^{\circ}\text{C}$	$I_R$	1 125							$\mu\text{A}$
Typical Junction Capacitance <sup>1)</sup>	$C_j$	30							pF
Typical Thermal Resistance <sup>2)</sup>	$R_{\theta JA}$	16							$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150							$^{\circ}\text{C}$

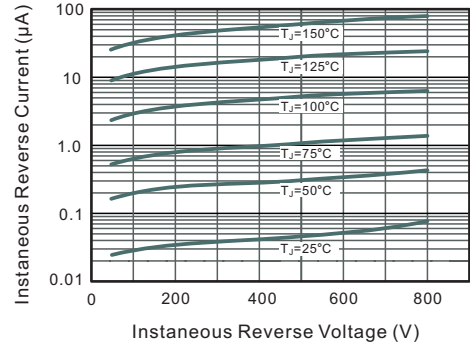
1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

2) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, P.C.B. mounted

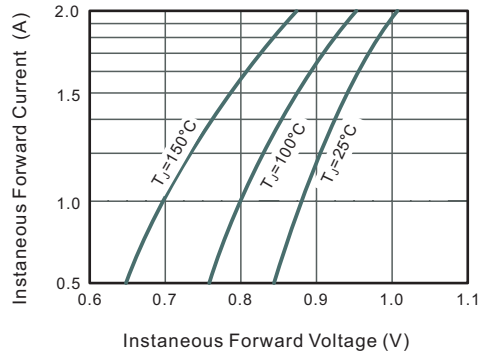
**Fig.1 Forward Current Derating Curve**



**Fig.2 Typical Instaneous Reverse Characteristics**



**Fig.3 Typical Forward Characteristic**



**Fig.4 Typical Junction Capacitance**

